Docket No.: Patton 03-1

## **AMENDMENTS TO THE CLAIMS:**

Please cancel claims 1-12 without prejudice or disclaimer, and amend claims 13 and 14 by way of replacement as follows:

1-12. (Cancelled).

13. (Currently amended) A method for assembling a power supply an electronic module, comprising the steps of:

providing at least one internal circuit board;

said at least one internal circuit board comprising a vent hole;

providing a case;

placing said at least one internal circuit board in said case;

plugging said vent hole; and

filling said case with potting compound

providing an electrical connector on said circuit board;

said electrical connector comprising a groove therein;

providing a clip; and

sliding said clip into said groove.

14. (Currently amended) The method according to claim 13, further comprising the steps of:

providing a board holder; and

placing said board holder on said circuit board[;]

providing a power inletconnector on said circuit board;

said power inletconnector comprising a groove therein providing a clip; and sliding said clip into said groove.

- 15. (Original) The method according to claim 13, further comprising the step of: baking said power supply.
- 16. (Original) The method according to claim 15, wherein:said power supply is baked at a temperature in the range from 80-120°C for a period of 5-15 minutes.
- 17. (Original) The method according to claim 16, wherein: said power supply is baked at 100°C for 10 minutes.
- 18. (Original) The method according to claim 15, further comprising the step of: after said power supply has cooled, unplugging said vent hole.
- 19. (Original) The method according to claim 13, further comprising the steps of:
  after said step of filling said case with potting compound, unplugging said vent hole.
- 20. (Original) The method according to claim 13, further comprising the step of: providing at least one locating groove in an interior surface of said case; locating said circuit board in said locating groove.

21. (Original) The method according to claim 13, further comprising the step of:

providing at least one notch in a lower edge of said case;

locating said circuit board in said notch.